

SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL03C090CA3GNNC
- Description : CAP, 9pF, 25V, ±0.25pF, C0G, 0201

A. Samsung Part Number

			<u>CL</u> ①	<mark>03</mark> ②	<u>C</u> 3	<u>090</u> ④	<u>C</u> 5	<u>A</u> 6	<u>3</u> 7	<u>G</u> ⑧	<u>N</u> 9	<u>N</u> 10	<u>C</u> 1			
1	Series	Samsung I	Multi-la	yer C	eram	ic Cap	acito	or								
2	Size	0201 (inch co	ode)		L:	0.6	± 0.0)3	mm		W:	0.3	± 0.03	mm	
3	Dielectric	C0G					8	Inne	r ele	ctrod	le		Cu			
4	Capacitance	9 p	ьF					Tern	ninat	ion			Cu			
5	Capacitance	±0.25 p	ъF					Plati	ng				Sn 10	0%	(Pb Fre	ee)
	tolerance						9	Proc	luct				Norm	al		
6	Rated Voltage	25 \	/				10	Spee	cial				Rese	rved for	future u	se
1	Thickness	0.3 ±	± 0.03	mm			1	Pack	cagir	ng			Cardb	board Ty	vpe, 7" r	eel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1M±±10% 0.5~5Vrms						
Q	580 min							
Insulation	10,000Mohm or 500Mohm · <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance No abnormal exterior appearance		Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	C0G							
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)							
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder						
	is to be soldered newly	235±5℃, 5±0.5sec.						
		2) SnAg3.0Cu0.5 solder						
		245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs					
	within $\pm 5\%$ or ± 0.5 pF whichever is larger						
	Q: 290 min						
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 130 min						
	IR : 500Mohm or 25Mohm $\cdot \mu F$						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 290 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	ightarrow Max. operating temperature $ ightarrow$ 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^\circ\!\mathrm{C}$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.